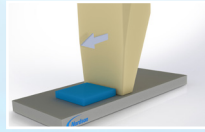
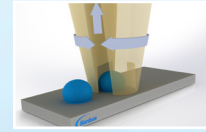


Wire Pull
For post wire bond
quality control



Die Shear
For die attach
verification



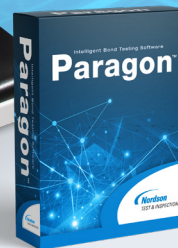
Tweezer Pull
For flip chip
reliability



Gold Standard Precision
Ultimate traceability
with Datasync™



Ergonomic Design
Microscope, keypads
and joysticks



**Paragon™ Lite
Software**
Easy-to-use in
production

STELLAR 4000 Bondtester

Industry Standard Production Bond Testing

STELLAR 4000 is the platform of choice for all manually operated pull and shear production Bond Testing. Configure as a simple bond wire pull tester, or upgrade for ball shear, die shear, bump pull, and tweezer pull testing.

For operator free production Bond Testing, consider the 4600 fully automatic Bondtester from Nordson TEST & INSPECTION.

STELLAR 4000 Industry Standard Production Bond Testing

Industry Leading Precision

Whether you utilize one Bondtester in production or many, STELLAR 4000 ensures ultimate system to system consistency so pass/fail decisions are the same, regardless of the Bondtester used.

- Patented frictionless load cartridge technologies guarantee accuracy, repeatability and correlation.
- Rugged, high quality frame is built to last, ensuring years of smooth operation.
- Conforms to industry testing standards and compatible with 4000 series cartridges.

Maximum Operator Comfort

STELLAR 4000 is extremely easy and comfortable to use so operators can test for prolonged periods without risk to their health.

- Working heights, and controls designed with the operator in mind.
- Soft, padded arm rests ensure STELLAR 4000 is a pleasure to use.
- Antivibration optics, and dimmable lighting reduce eye strain during long sessions.

Perfect for Semiconductor

STELLAR 4000 is designed specifically for the needs of semiconductor manufacturing.

- Clean room friendly, enclosed design.
- Assessed to SEMI S2 environmental health and safety, and SEMI S8 ergonomic standards.
- Fast setup and intuitive Paragon™ Lite software ensures you can release into production quickly.

Key Features		Semiconductor Testing Standards	
Software	Paragon Lite	Bump shear	JESD22-B117B JEITA-ET-7409
PC connection	Ethernet	Cold bump pull	JESD22-B115A JEITA-ET-7409
Air supply safety	Tool protection & air warning	Die shear	MIL-STD-883 IPC-TM-650
EMO switch position	Left keypad		
Illumination	Software dimmable LED		
Table type	Integrated & enclosed		
Performance		Semi Packaging Testing Standards	
Step back accuracy	± 1 µm	Ball bond shear	MIL-STD-883 ASTM-F1269
System accuracy	± 0.25 % FSL	Wire pull	JESD22-B116B MIL-STD-883 IPC-TM-650
Axis travel (X × Y × Z)	100 mm × 100 mm × 65 mm		
XY speed and resolution	Up to 2 mm/s, 500 nm		
Z speed and resolution	5 mm/s, 250 nm		
Installation		Certification	
Footprint (W × D × H)	705 mm × 562 mm × 675 mm	SEMI standards	S2 & S8
Weight	86 kg	CE compliance	Machinery, EMC & RoHS
Power supply	100 - 240 VAC single phase	Factory accreditation	ISO 9001:2015
Pneumatic supply	Min 4.0 bar	Environmental	ROHS (2011/65/EU)

For more information, speak with your Nordson representative or contact your Nordson regional office

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